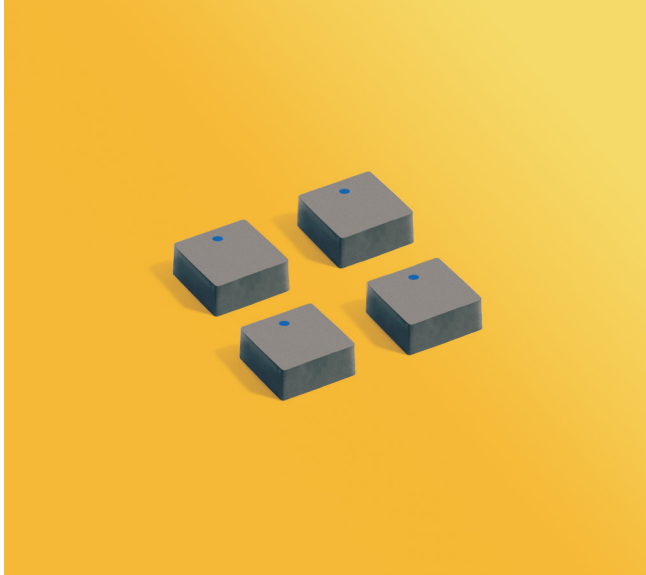


Outgassing Compliant Power Inductors AE433PZA



- High temperature materials allow operation in ambient temperatures up to 155°C
- Passes NASA low outgassing specifications
- Tin-lead (Sn-Pb) termination for the best possible board adhesion
- Exceptionally low DCR; soft saturation
- Passes vibration testing to 30 G and shock testing to 500 G

Terminations Tin-lead (63/37) over copper.

Core material Composite

Weight 134 – 187 mg

Ambient temperature –55°C to +105°C with Irms current

Maximum part temperature +155°C (ambient + temp rise).

Storage temperature Component: –55°C to +155°C.

Tape and reel packaging: –55°C to +80°C

Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C / 85% relative humidity)

Enhanced crush-resistant packaging 1000/7" reel

Plastic tape: 12 mm wide, 0.23 mm thick, 8 mm pocket spacing, 2.3 mm pocket depth

Part number ¹	Inductance ² ±20% (µH)	DCR (mOhms) ³		SRF (MHz) ⁴		Isat (A) ⁵			Irms (A) ⁶	
		typ	max	min	typ	10% drop	20% drop	30% drop	20°C rise	40°C rise
AE433PZA102MSZ	1.0	10.80	11.90	51	64	4.5	5.1	5.4	6.0	8.3
AE433PZA152MSZ	1.5	14.40	15.80	47	59	4.1	4.4	4.6	5.0	6.8
AE433PZA222MSZ	2.2	21.35	23.50	30	38	3.1	3.5	3.7	4.5	6.0
AE433PZA332MSZ	3.3	34.80	38.30	26	33	2.7	2.8	2.9	2.9	3.9
AE433PZA472MSZ	4.7	52.20	57.40	21	26	2.0	2.5	2.7	2.7	3.6

1. When ordering, please specify **testing** code:

Testing: **AE433PZA472MSZ**
Z = Unscreened
H = Group A screening per Coilcraft CP-SA-10001
T = Screening per MIL-STD-981
U = Screening per EEE-INST-002
F = Screening per ESCC 3201
 All screening performed to the document's latest revision
 Custom screening also available

2. Inductance tested at 100 kHz, 0.1 Vrms, 0 Adc.

3. DCR measured on a micro-ohmmeter.

4. SRF measured using an Agilent/HP 4395A or equivalent.

5. DC current at 25°C that causes the specified inductance drop from its value without current.

6. Current that causes the specified temperature rise from 25°C ambient.
 This information is for reference only and does not represent absolute maximum ratings.

7. Electrical specifications at 25°C.

Refer to Doc 362 "Soldering Surface Mount Components" before soldering.

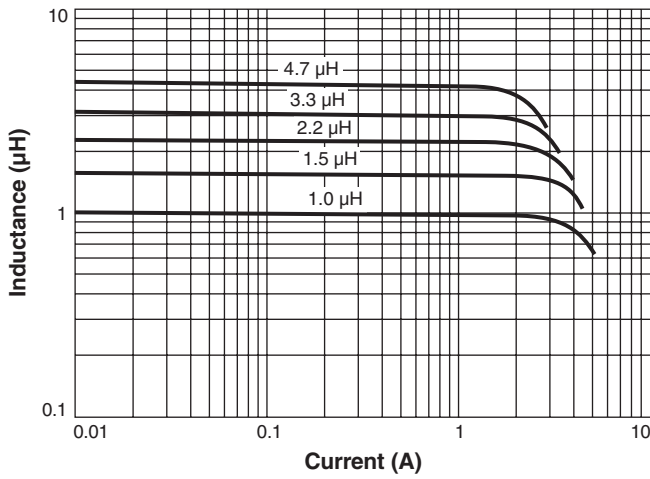
Irms Testing

Irms testing was performed on a 0.060" thick pcb with 4 oz. copper traces optimized to minimize additional temperature rise.

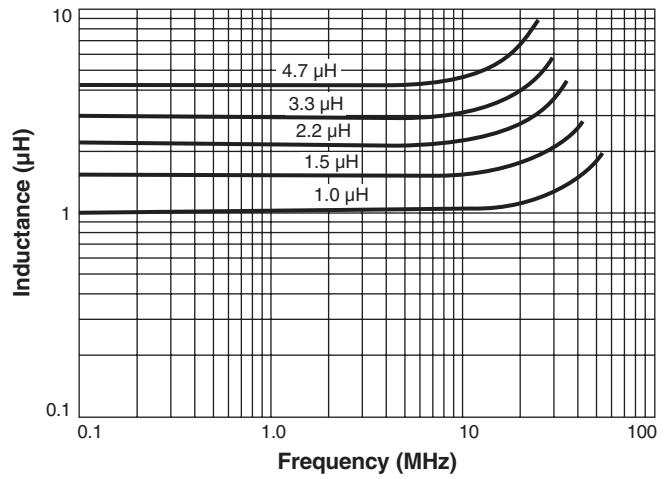
Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.

AE433PZA Series

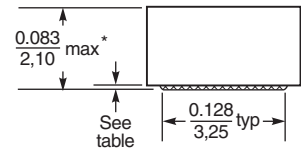
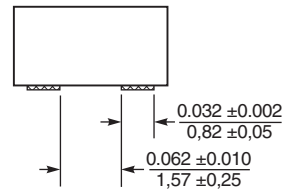
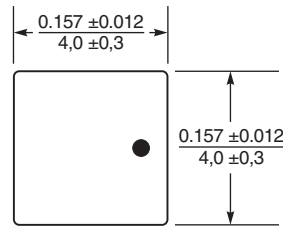
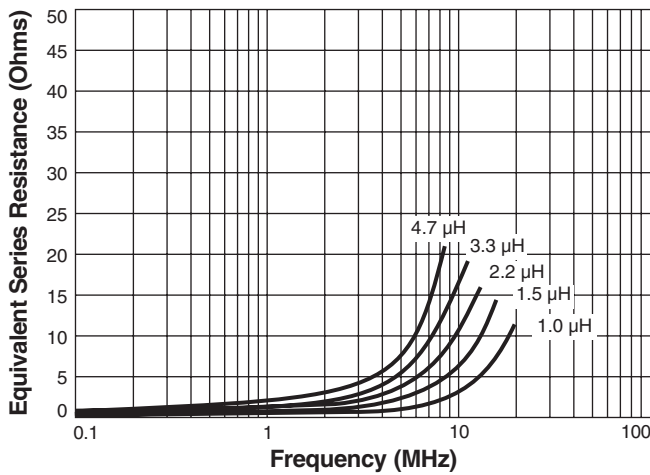
L vs Current



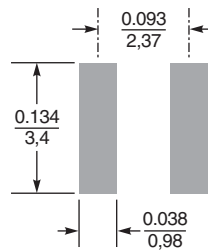
L vs Frequency



ESR vs Frequency



Dash number	Terminal thickness (typ) (in / mm)
-102	0.0039 / 0.10
-152	0.0039 / 0.10
-222	0.0032 / 0.08
-332	0.0023 / 0.06
-472	0.0023 / 0.06



Suggested Land Pattern

* Height dimension shown is for the mounted part after reflow. Dimension before mounting can be an additional 0.008 inch / 0.2 mm.

Dimensions are in $\frac{\text{inches}}{\text{mm}}$